

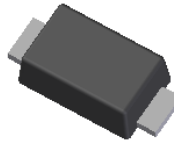
Features

- Ultra-Low Forward Voltage Drop
- Superior Reverse Avalanche Capability
- Patented Interlocking Clip Design for High Surge Current Capacity
- Patented Super Barrier Rectifier (SBR[®]) Technology
- Soft, Fast Switching Capability
- +150°C Operating Junction Temperature
- ±16KV ESD Protection (HBM, 3B)
- ±25KV ESD Protection (IEC61000-4-2 Level 4, Air Discharge)
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at <https://www.diodes.com/products/automotive/automotive-products/>.**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.**
<https://www.diodes.com/quality/product-definitions/>

Mechanical Data

- Case: PowerDI[®]123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity Indicator: Cathode Band
- Terminals: Matte Tin Finish Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 ^(E3)
- Weight: 0.018 grams (Approximate)

PowerDI123



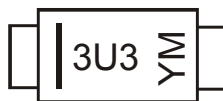
Top View

Ordering Information (Note 4)

Part Number	Case	Packaging
SBR3U30P1-7	PowerDI123	3000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3).compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>

Marking Information



3U3 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: G = 2019)
 M = Month (ex: 9 = September)

Date Code Key

Year	2006	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028
Code	T		G	H	I	J	K	L	M	N	O	P

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Rectified Output Current (See Figure 1)	I _O	3.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms	I _{FSM}	75	A
Single Half Sine-Wave Superimposed on Rated Load			
Non-Repetitive Avalanche Energy (T _J = +25°C, I _{AS} = 5A, L = 8.5mH)	E _{AS}	105	mJ
Repetitive Peak Avalanche Energy (1μs, +25°C)	P _{ARM}	1,100	W

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance	R _{θJS}	5	°C/W
Thermal Resistance Junction to Soldering (Note 5)	R _{θJA}	178	
Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	123	
Thermal Resistance Junction to Ambient (Note 7)			
Operating and Storage Temperature Range (Note 8)	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	V _{(BR)R}	30	—	—	V	I _R = 400μA
Forward Voltage Drop	V _F	—	0.28	0.32	V	I _F = 0.5A, T _J = +25°C
			0.31	0.35		I _F = 1.0A, T _J = +25°C
			0.39	0.43		I _F = 3.0A, T _J = +25°C
			0.20	0.23		I _F = 0.5A, T _J = +125°C
			0.23	0.26		I _F = 1.0A, T _J = +125°C
Leakage Current (Note 8)	I _R	—	70	150	μA	V _R = 5V, T _J = +25°C
			150	400	μA	V _R = 30V, T _J = +25°C
			6	15	mA	V _R = 5V, T _J = +125°C
			12	20	mA	V _R = 30V, T _J = +125°C

- Notes:
- Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
 - FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/package-outlines.html>.
 - Polymide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/package-outlines.html>.
 - Short duration pulse test used to minimize self-heating effect.

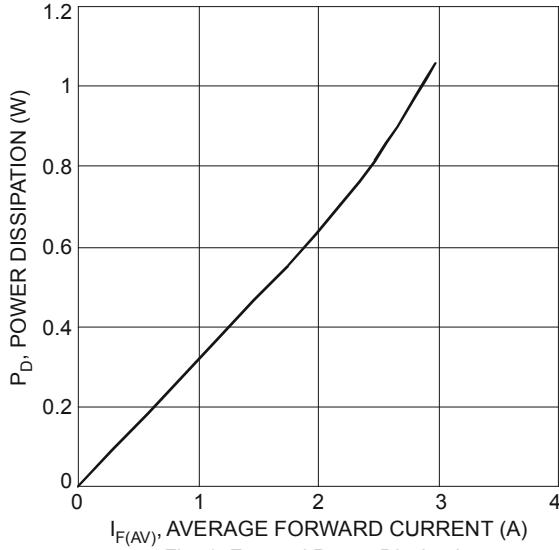


Fig. 1 Forward Power Dissipation

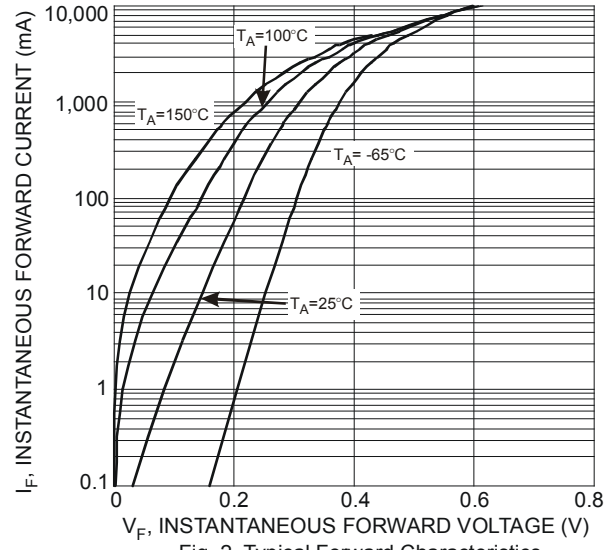


Fig. 2 Typical Forward Characteristics

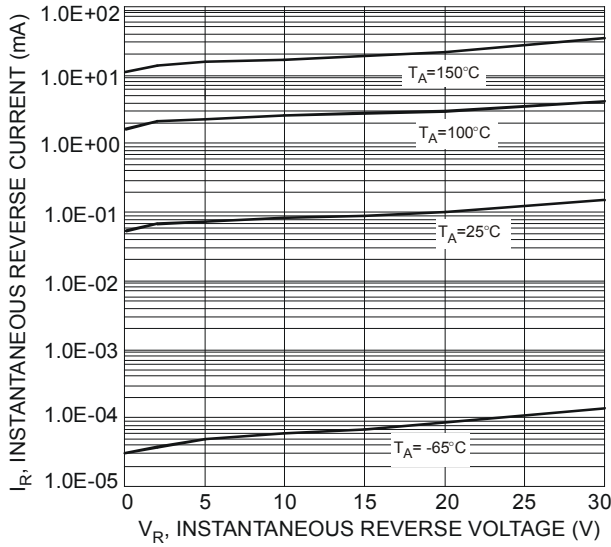


Fig. 3 Typical Reverse Characteristics

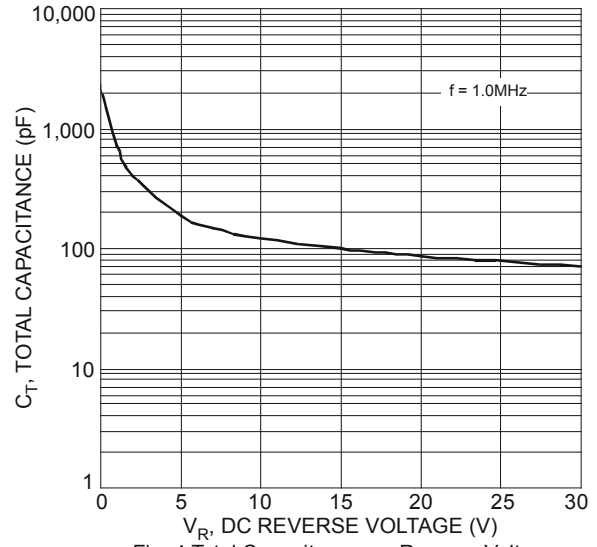


Fig. 4 Total Capacitance vs. Reverse Voltage

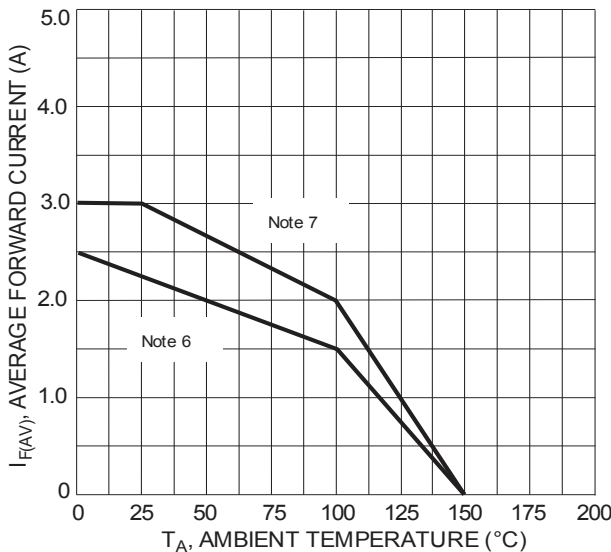


Fig. 5 Forward Current Derating Curve

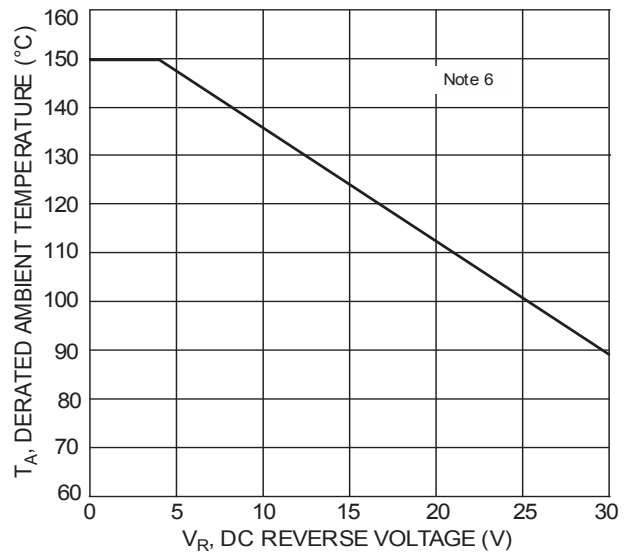


Fig. 6 Operating Temperature Derating

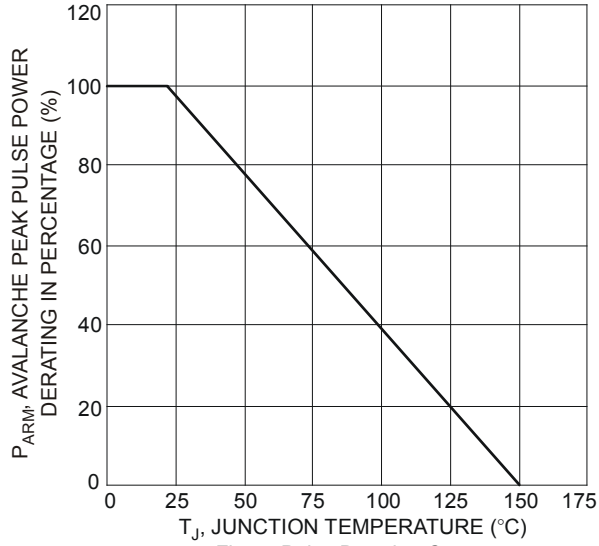


Fig. 7 Pulse Derating Curve

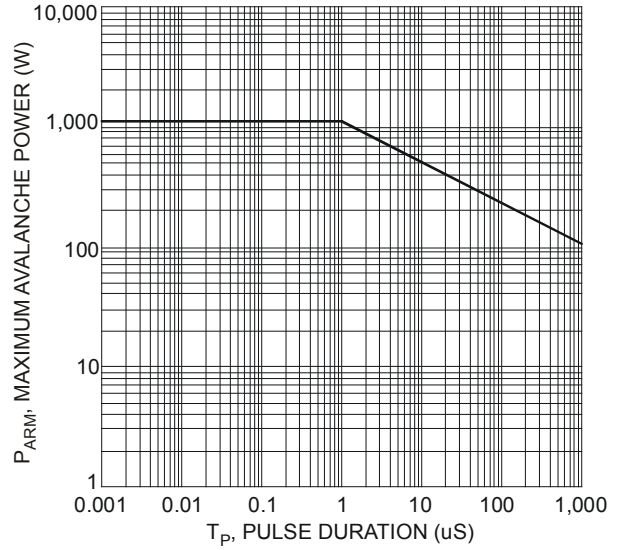


Fig. 8 Maximum Avalanche Power Curve

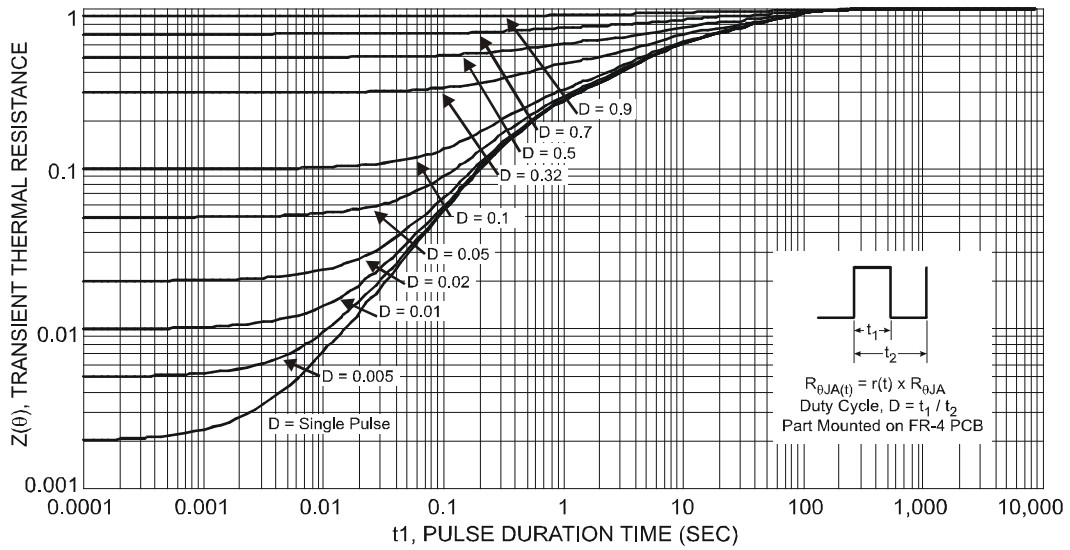
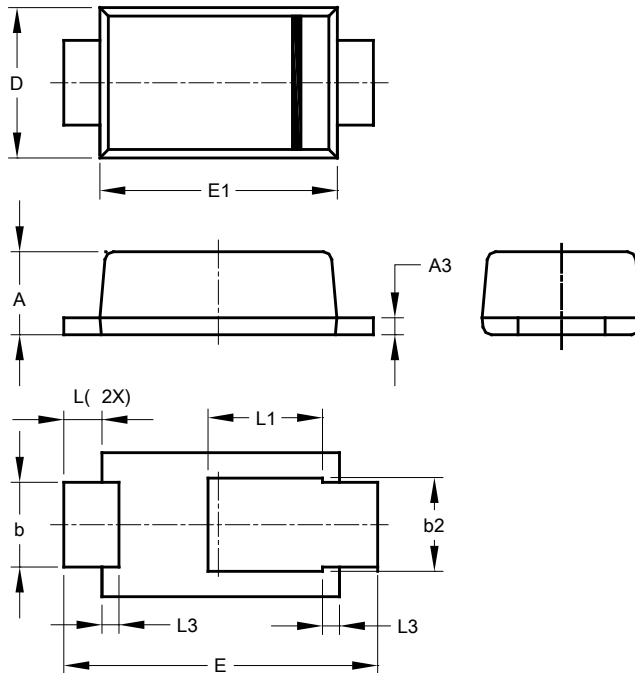


Fig. 9 Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123

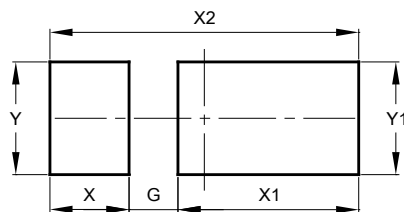


PowerDI123			
Dim	Min	Max	Typ
A	0.93	1.00	0.98
A3	0.15	0.25	0.20
b	0.85	1.25	1.00
b2	1.025	1.125	1.10
D	1.63	1.93	1.78
E	3.50	3.90	3.70
E1	2.60	3.00	2.80
L	0.40	0.50	0.45
L1	1.25	1.40	1.35
L3	0.125	0.275	0.20
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123



Dimensions	Value (in mm)
G	0.65
X	1.05
X1	2.40
X2	4.10
Y	1.50
Y1	1.50

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